

53. The piezoelectric/electrostrictive film element in Claim 39, wherein said organic solvent which is a base of said ceramic sol solution is acetic acid, dimethyl formamide, methoxyethanol, alcohols, or glycols.

5 54. The piezoelectric/electrostrictive film element in Claim 39, wherein the content of said ceramic sol solution is 1-500 parts by weight based on the weight of said ceramic oxide powder when the suspension of said ultrafine ceramic oxide powder and said ceramic sol solution are mixed.

10 55. The piezoelectric/electrostrictive film element in Claim 39, wherein the thickness of said piezoelectric/electrostrictive film element is 1-100 μm .

15 56. The piezoelectric/electrostrictive film element in Claim 55, wherein the thickness of said piezoelectric/electrostrictive film element is 5-30 μm .

57. The piezoelectric/electrostrictive film element in Claim 39, wherein said piezoelectric/electrostrictive film element is thermally thermaled at 150-300°C.